

**Features**

- $BV_{CEO} > 60V$
- Max continuous current  $I_C = 1A$
- $h_{FE} > 100$  @  $I_C = 150mA$ ,  $V_{CE} = 150mV$
- **Lead Free, RoHS Compliant (Note 1)**
- **Halogen and Antimony Free "Green" Device (Note 2)**
- **Qualified to AEC-Q101 Standards for High Reliability**

**Applications**

- LED TV backlight

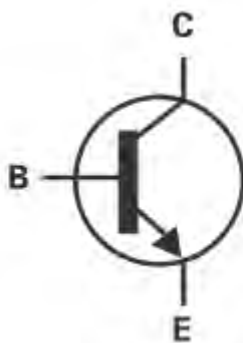
**Mechanical Data**

- Case: SOT89
- Case material: molded Plastic. "Green" molding Compound.
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish
- Weight: 0.052 grams (Approximate)

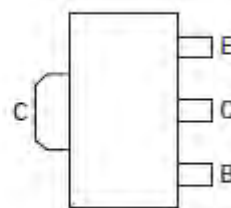
SOT89



Top View



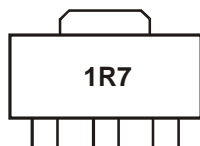
Device symbol


 Top View  
 Pin Out

**Ordering Information** (Note 3)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTN4000ZTA	1S7	7	12	1000 units

- Notes:
1. No purposefully added lead.
  2. Diodes Inc's "Green" Policy can be found on our website at <http://www.diodes.com>
  3. For Packaging Details, go to our website at <http://www.diodes.com>.

**Marking Information**


1R7 = Product Type Marking Code

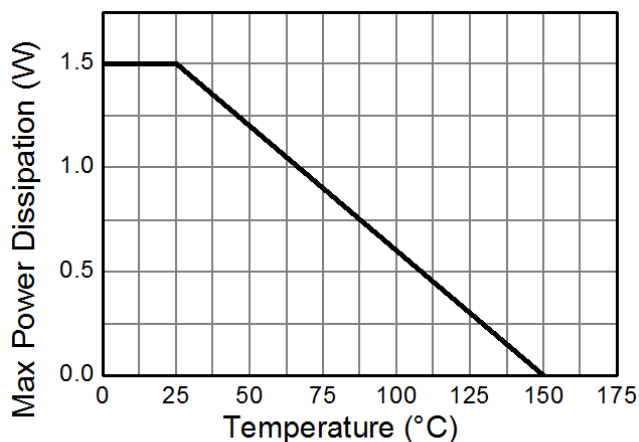
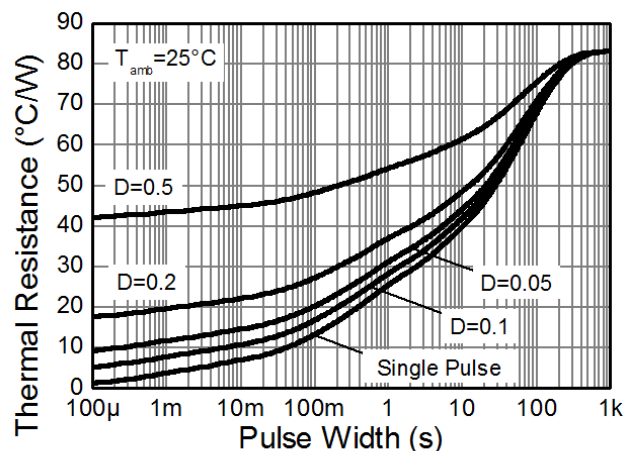
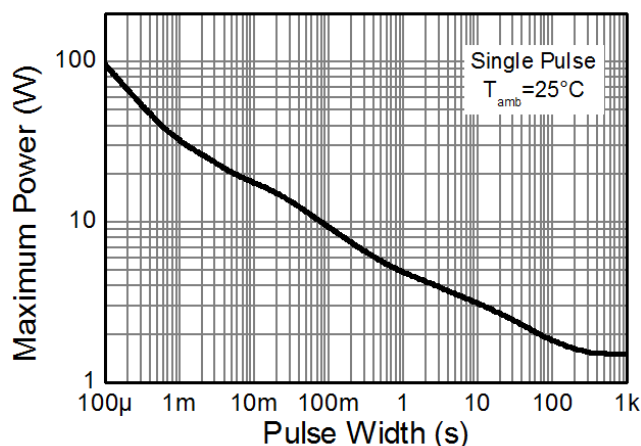
**Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	60	V
Collector-Emitter Voltage	V <sub>CEO</sub>	60	V
Emitter-Base Voltage	V <sub>EBO</sub>	7	V
Continuous Collector Current	I <sub>C</sub>	1	A
Peak Pulse Current (Note 4)	I <sub>CM</sub>	3	A
Base Current	I <sub>B</sub>	500	mA

**Thermal Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	1.5	W
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	83	°C/W
Thermal Resistance, Junction to Leads (Note 6)	R <sub>θJL</sub>	28	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

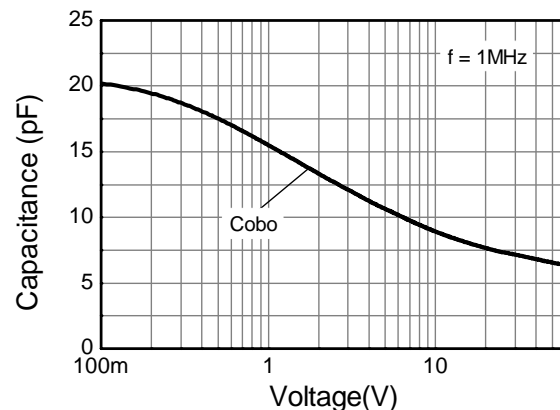
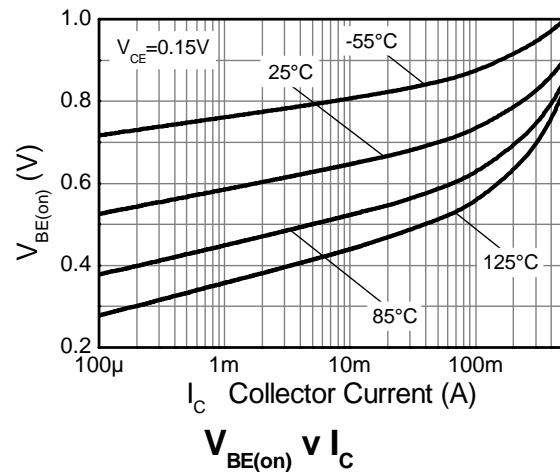
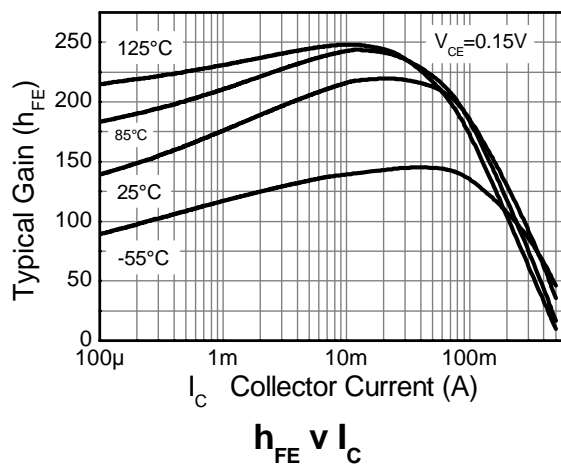
- Notes:
4. Measured under pulsed conditions. Pulse width = 300μs. Duty cycle ≤ 2%.
  5. For a device surface mounted on 25mm X 25mm FR4 PCB with high coverage of single sided 1 oz copper, in still air conditions
  6. Thermal resistance from junction to solder-point (at the end of the collector lead).

**Thermal Characteristics and Derating information**

**Derating Curve**

**Transient Thermal Impedance**

**Pulse Power Dissipation**

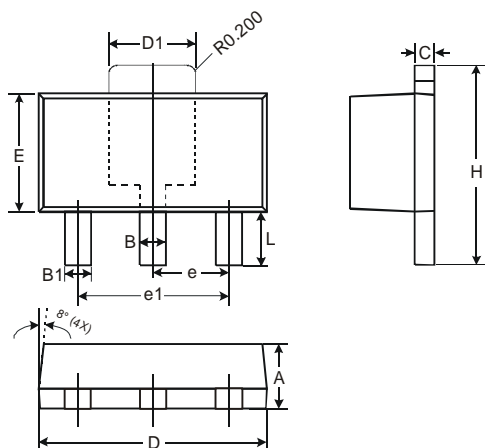
**Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	60		-	V	I <sub>C</sub> = 100μA
Collector-Emitter Breakdown Voltage (Note 7)	BV <sub>CEO</sub>	60		-	V	I <sub>C</sub> = 10mA
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	7	8.3	-	V	I <sub>E</sub> = 100μA
Collector Cut-off Current	I <sub>CBO</sub>	-	-	50	nA	V <sub>CB</sub> = 60V
Emitter Cut-off Current	I <sub>EBO</sub>	-	-	50	nA	V <sub>EB</sub> = 7V
Static Forward Current Transfer Ratio (Note 7)	h <sub>FE</sub>	60 100	- -	- -	-	I <sub>C</sub> = 85mA, V <sub>CE</sub> = 0.1V I <sub>C</sub> = 150mA, V <sub>CE</sub> = 0.15V
Base-Emitter Turn-On Voltage (Note 7)	V <sub>BE(on)</sub>	-	0.76	0.95	V	I <sub>C</sub> = 150mA, V <sub>CE</sub> = 0.15V
Delay Time	t <sub>d</sub>	-	300	-	ns	V <sub>CC</sub> = 48V, I <sub>C</sub> = 150mA, -I <sub>B2</sub> = 1.5mA, V <sub>CE(ON)</sub> = 0.15V
Rise Time	t <sub>r</sub>	-	292	-	ns	
Storage Time	t <sub>s</sub>	-	805	-	ns	
Fall Time	t <sub>f</sub>	-	226	-	ns	V <sub>CC</sub> = 48V, I <sub>C</sub> = 150mA, -I <sub>B2</sub> = 1.5mA, V <sub>CE(ON)</sub> = 4V
Storage Time	t <sub>s</sub>	-	25	-	ns	
Fall Time	t <sub>f</sub>	-	202	-	ns	

Notes: 7. Measured under pulsed conditions. Pulse width = 300μs. Duty cycle ≤ 2%

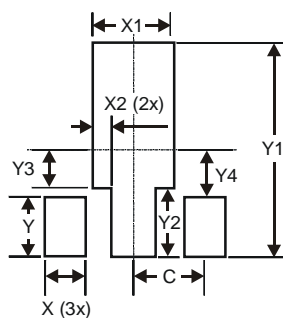
**Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

**Capacitance v Voltage**

## Package Outline Dimensions



SOT89		
Dim	Min	Max
A	1.40	1.60
B	0.44	0.62
B1	0.35	0.54
C	0.35	0.43
D	4.40	4.60
D1	1.52	1.83
E	2.29	2.60
e	1.50 Typ	
e1	3.00 Typ	
H	3.94	4.25
L	0.89	1.20
All Dimensions in mm		

## Suggested Pad Layout



Dimensions	Value (in mm)
X	0.900
X1	1.733
X2	0.416
Y	1.300
Y1	4.600
Y2	1.475
Y3	0.950
Y4	1.125
C	1.500

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